## SF1093A

- Designed for GSM BTS Transmitter IF Applications
- Low Insertion Loss
- Excellent Size-to-Performance Ratio
- Hermetic 13.3 x 6.5 mm Surface-Mount Case
- Unbalanced Input and Output
- Complies with Directive 2002/95/EC (RoHS)


## Absolute Maximum Ratings

| Rating | Value | Units |
| :--- | :---: | :---: |
| Maximum Incident Power in Passband | +10 | dBm |
| Max. DC voltage between any 2 terminals | 30 | VDC |
| Storage Temperature Range | -40 to +85 | ${ }^{\circ} \mathrm{C}$ |
| Suitable for lead-free soldering - Max. Soldering Profile | $260^{\circ} \mathrm{C}$ for 30 s |  |

## 175 MHz SAW Filter



SM13365-12

## Electrical Characteristics

| Characteristic | Sym | Notes | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Nominal Center Frequency | ${ }^{\text {f }}$ | 1 | 175.000 |  |  | MHz |
| Passband Insertion Loss at fc | IL |  |  | 8 | 9.0 | dB |
| 2 dB Passband <br> Amplitude Ripple (peak to adjacent valley) <br> Amplitude Variation over fc $\pm 200 \mathrm{kHz}$ <br> Group Delay Variation over fc $\pm 300 \mathrm{kHz}$ <br> Absolute Group Delay | $\mathrm{BW}_{2}$ | 1, 2 | $\pm 330$ | $\pm 460$ |  | kHz |
|  |  |  |  |  | 0.5 | $\mathrm{dB}_{\mathrm{P}-\mathrm{P}}$ |
|  |  |  |  |  | 1.0 |  |
|  | GDV |  |  | <200 | 260 | $n S_{\text {P-P }}$ |
|  | GD |  |  | 1.3 | 1.5 | $\mu \mathrm{s}$ |
| Rejectionfc-0.9 to fc-0.6 and fc +0.6 to fc +0.9 MHz <br> $\mathrm{fc}-1.2$ to fc-0.9 and fc+0.9 to fc +1.2 MHz <br> fc-6.0 to fc-1.2 and fc +1.2 to fc +6.0 MHz <br> fc-155 to fc-6.0 and fc +6.0 to fc +125 MHz |  | 1, 2, 3 | 5 |  |  | dB |
|  |  |  | 17 |  |  |  |
|  |  |  | 30 |  |  |  |
|  |  |  | 50 |  |  |  |
| Operating Temperature Range | TA | 1 | -5 |  | +70 | ${ }^{\circ} \mathrm{C}$ |


| Impedance Matching to $50 \Omega$ unbalanced | External L-C |
| :--- | :---: |
| Case Style | SM13365-12 $13.3 \times 6.5 \mathrm{~mm}$ Nominal Footprint |
| Lid Symbolization (YY = year, WW $=$ week $)$ | RFM SF1093A YYWW |

## Notes:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 W and measured with $50 \Omega$ network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
7. US and international patents may apply.
8. Electrostatic Sensitive Device. Observe precautions for handling.

## Electrical Connections

| Connection | Terminals |
| :--- | :---: |
| Port 1 Hot | 2 |
| Port 1 Gnd Return | 3 |
| Port 2 Hot | 8 |
| Port 2 Gnd Return | 9 |
| Case Ground | All others |




## SM13365-12 Case

## 12-Terminal Ceramic Surface-Mount Case <br> $13.3 \times 6.5 \mathrm{~mm}$ Nominal Footprint



| Case Dimensions |  |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Dimension | mm |  |  | Inches |  |  |  |
|  | Min | Nom | Max | Min | Nom | Max |  |
| A | 13.08 | 13.31 | 13.60 | 0.515 | 0.524 | 0.535 |  |
| B | 6.27 | 6.50 | 6.80 | 0.247 | 0.256 | 0.268 |  |
| C |  | 1.91 | 2.00 |  | 0.075 | 0.079 |  |
| D |  | 1.50 |  |  | 0.059 |  |  |
| E |  | 0.79 |  |  | 0.031 |  |  |
| H |  | 1.0 |  |  | 0.039 |  |  |
| P |  | 2.54 |  |  | 0.100 |  |  |


| Materials |  |
| :--- | :--- |
| Solder Pad <br> Termination | Au plating 30-60 ulnches (76.2-152 uM) over 80- <br> 200 ulnches (203-508 uM) Ni. |
| Lid | Fe-Ni-Co Alloy Electroless Nickel Plate (8-11\% <br> Phosphorus) 100-200 ulnches Thick |
| Body | $\mathrm{Al}_{2} \mathrm{O}_{3}$ Ceramic |
| Pb Free |  |


| Clectrical Connections |  |  |
| :--- | :--- | :---: |
| Connection |  | Terminals |
| Port 1 | Input or Return | 2 |
|  | Return or Input | 3 |
| Port 2 | Output or Return | 8 |
|  | Return or Output | 9 |
|  | Ground | All others |
| Single Ended Operation |  | Return is ground |
| Differential Operation |  | Return is hot |



3. LABEL FIXTURE WITH ELECTRONIC METHOD AS SHOWN.
4. SOLDER J1 \& J2 TO PCB1 AS SHOWN.


$\square$



## BILL OF MATERIALS

PART IDENTIFIER
SF1093A-DEMO
SF1093A-000
400-1412-001
500-0003-270
500-0003-330
500-0248-001
500-0010-150
500-0010-047

DESCRIPTION 1
DEMO BOARD,SF1093A
ASSY DIAGRAM,DEMO BOARD
PCB, DEMO, 13MM, TYPE 2
CAP,CHIP,NPO,27(J),STD
CAP,CHIP,NPO,33(J),STD
CONN,COAX,FLANGE MT.JACK
IND,CHIP,1008CS,15NH,10\%
IND,CHIP,1008CS,4.7NH,10\%

DESCRIPTION 2
QTY/ASSY
REFERENCE DESCRIPTION

SF1093A
0
1.0000 PCB
1.0000 C 1
1.0000 C 2
2.0000 J 1,2
2.0000 L 1,4
2.0000 L 2,3

